162162
G00002

WAFER-LEVEL PACKAGE FOR MICRO-ELECTRO-MECHANICAL SYSTEMS

Abstract

A method for forming wafers having through-wafer vias for wafer-level packaging of devices, the method comprising the steps of depositing a metal layer on one of a first wafer and a second wafer; bonding the first wafer and the second wafer using the metal layer deposited on one of the first wafer and the second wafer; forming a through-wafer via in one of the first wafer and the second wafer; filling the through-wafer via with a conductive material; and forming a cavity in the one of the first wafer and the second wafer having the through-wafer via, wherein the cavity is superposable over a device.

Figure 3G